

Product features

High precision machining technology

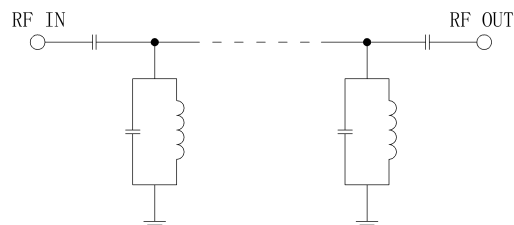
Low temperature drift, high power.

Ceramic substrate, 50 Ω coplanar waveguide

Gold wire bonding



Schematic diagram



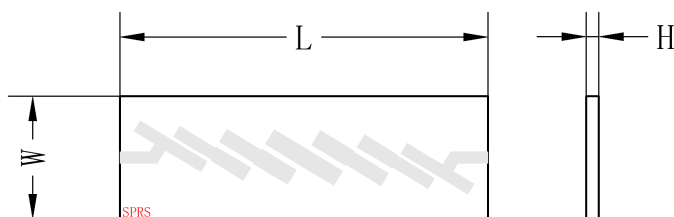
Tech specifications

Items	Parameters	Units
Center Frequency	12.0	GHz
Bandwidth	0	GHz
Center loss	6.5	dB
Ripple	0	dB
VSWR	1.7:1	
Group delay ripple	0	ns
Rejection	35@DC-11.4GHz	dBc
Rejection	35@12.6-20.0GHz	dBc

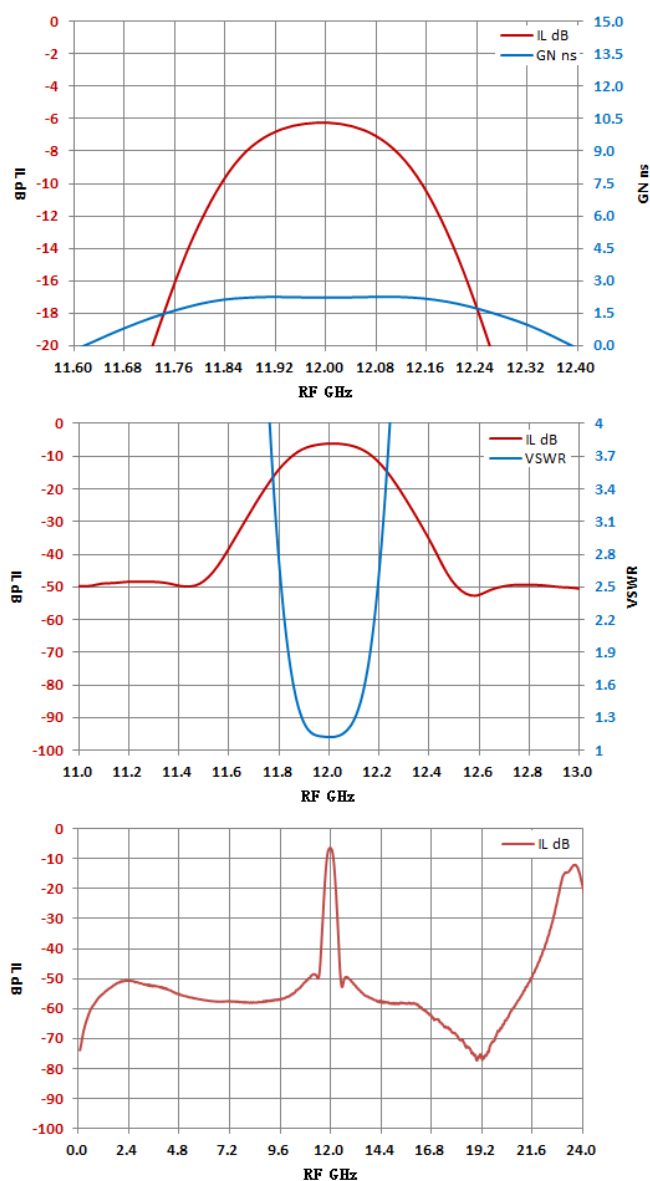
Other requirement (Design assurance)

power	1W CW
Work Temp.	-55~+85°C
Storage Temp.	-55~+125°C
Outline size	L:6.0, W:4.0, h:0.26

Outline drawing: Port centered

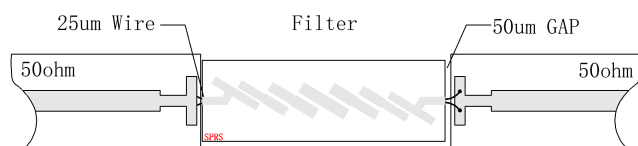


Typical test curve



Note: The specifications and performance data contained in this data sheet are based on tests established by CMW.

Suggested PCB Layout



PCB Rogers5880, h: 0.254mm	PCB Rogers4350B, h: 0.254mm
	

Note

- 1: 0.1mm from the side wall, 2.75mm from the surface to the upper cover.
- 2: Suggest using conductive adhesive for bonding;
- 3: The chip should be installed on kovar alloy or molybdenum copper;
- 4: Suggest using a T-shaped structure for microstrip bonding.